

IN THE CLAIMS:

Please add new claims 12-21 in favor of previous claims 1-11 which are hereby canceled in their entirety without prejudice or disclaimer of the subject matter set forth therein.

1-11. (Canceled)

12. (New) A semiconductor device comprising:

a wiring board;

a first semiconductor chip and a second semiconductor chip, each of which has a circuitry side and a non-circuitry side that face each other vertically and each of which is electrically connected to the wiring board via raised electrodes, the circuitry side of the first and second chips facing the principal surface of the wiring board; and

a third semiconductor chip, which has a circuitry side and a non-circuitry side that face each other vertically and which includes external electrodes on the circuitry side thereof,

wherein the non-circuitry sides of the third semiconductor chips are secured to the non-circuitry side of the first semiconductor chip and the non-circuitry side of the second semiconductor chip,

wherein the external electrodes of the third semiconductor chip are connected to the wiring board via metal fine wires, and

wherein the external electrodes are disposed so as not to overlap with the raised electrodes.

13. (New) The device of claim 12, wherein the first semiconductor chip, the second semiconductor chip and third semiconductor chip have a thickness of 300 μ m or lower.

14. (New) The device of claim 12, wherein the external electrodes are provided on the inner side of the second semiconductor chip and the third semiconductor chip with respect to the raised electrodes.

15. (New) The device of claim 12, wherein the external electrodes are disposed so as to align, and wherein the raised electrodes are disposed so as to align.

16. (New) The device of claim 12, wherein the raised electrodes and the wiring board are secured to each other with a conductive adhesive.

17. (New) The device of claim 12, wherein the raised electrodes and the wiring board are secured to each other with a low-melting metal.

18. (New) The device of claim 12, wherein the raised electrodes are in direct contact with the principle surface of the wiring board.

19. (New) The device of claim 12, wherein the first semiconductor chip, the second semiconductor chip and third semiconductor chip are LSI chips.

20. (New) The device of claim 19, wherein the combination of chips is a logic chip and a memory chip.

21. (New) The device of claim 12, wherein side faces of the second and third semiconductor chips are on the inner side of the side faces of the first semiconductor chip.